

**Features**

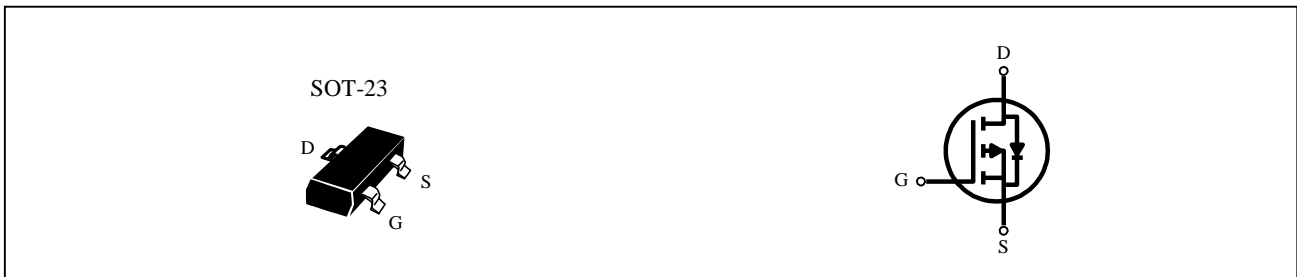
Super high dense cell trench design for low  $R_{DS(on)}$ .

Rugged and reliable.

Surface Mount package.

**PRODUCT SUMMARY**

$V_{DSS}$	$I_D$	$R_{DS(on)}$ (m $\Omega$ ) Max
-30V	- 3.7A	70 @ $V_{GS} = -10V$
	- 3.0A	95 @ $V_{GS} = -4.5V$

**Mechanical Data**

**ABSOLUTE MAXIMUM RATINGS** ( $T_C=25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous <sup>a</sup> @ $T_A = 25^\circ\text{C}$ -Pulse <sup>b</sup>	$I_D$	-3.7	A
	$I_{DM}$	-14	A
Drain-Source Diode Forward Current <sup>a</sup>	$I_S$	-1.9	A
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A=25^\circ\text{C}$	1.25
		$T_A=75^\circ\text{C}$	0.75
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	- 55 to 150	$^\circ\text{C}$

**THERMAL DATA**

Thermal Resistance, Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	100	$^\circ\text{C/W}$
--	------------	-----	--------------------

Note :

a. Surface Mounted on FR4 Board ,  $t = 10\text{sec}$  .

b. Pulse width limited by maximum junction temperature.

**ELECTRICAL CHARACTERISTICS** ( $T_c=25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -24V, V_{GS} = 0V$			-1	$\mu A$
Gate-Body Leakage	$I_{GSS}$	$V_{GS} = -20V, V_{DS} = 0V$			-100	nA
<b>ON CHARACTERISTICS<sup>b</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-3	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -3.7A$		56	70	m
		$V_{GS} = -4.5V, I_D = -3.0A$		73	95	
Forward Transconductance	$g_{fs}$	$V_{DS} = -15V, I_D = -3.5A$		10.2		S
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>b</sup></b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0V, I_S = -1.9A$			-1.3	V
<b>DYNAMIC CHARACTERISTICS<sup>c</sup></b>						
Input Capacitance	$C_{ISS}$	$V_{DS} = -15V, V_{GS} = 0V$ $f = 1.0MHz$		490		pF
Output Capacitance	$C_{OSS}$			66		pF
Reverse Transfer Capacitance	$C_{RSS}$			53		pF
<b>SWITCHING CHARACTERISTICS<sup>c</sup></b>						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD} = -15V, I_D = -1A$ $V_{GEN} = -10V$ $R_L = 15$ $R_{GEN} = 6$		4.4		ns
Rise Time	$t_r$			2.2		ns
Turn-Off Delay Time	$t_{D(OFF)}$			22		ns
Fall Time	$t_f$			4.2		ns
Total Gate Charge	$Q_g$	$V_{DS} = -15V$ $I_D = -1A$ $V_{GS} = -10V$		10		nC
Gate-Source Charge	$Q_{gs}$			1.5		nC
Gate-Drain Charge	$Q_{gd}$			1.4		nC

Note :

b. Pulse Test : Pulse width 300 $\mu s$ , Duty Cycle 2% .

c. Guaranteed by design, not subject to production testing .

**TYPICAL CHARACTERISTICS**

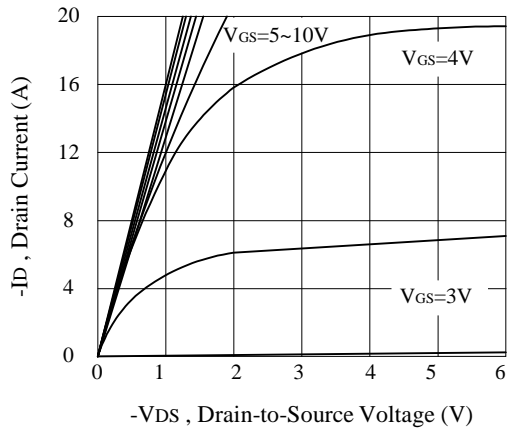


Figure 1. Output Characteristics

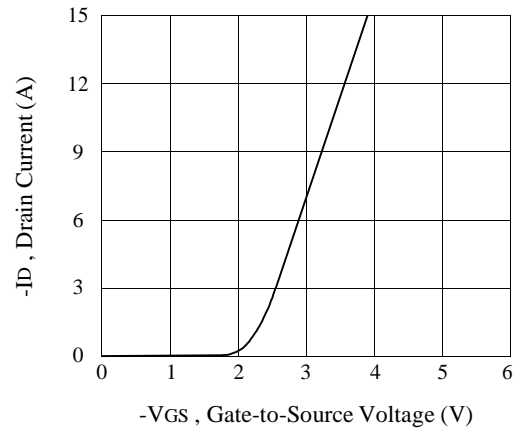


Figure 2. Transfer Characteristics

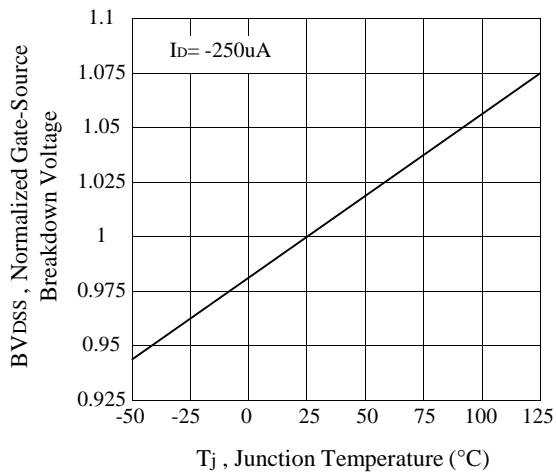


Figure 3. Breakdown Voltage Variation with Temperature

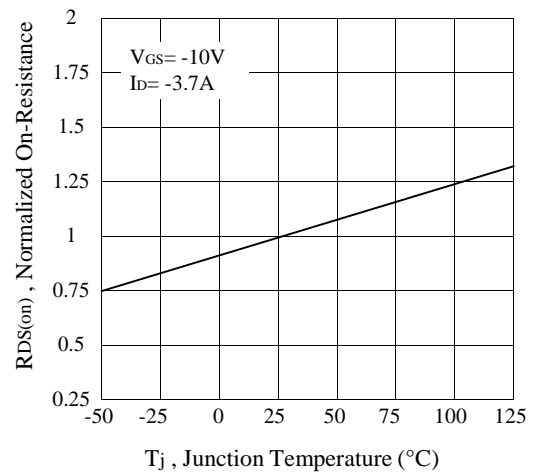


Figure 4. On-Resistance Variation with Temperature

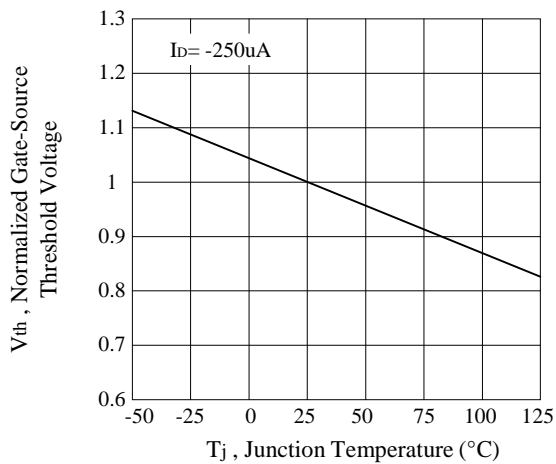


Figure 5. Gate Threshold Variation with Temperature

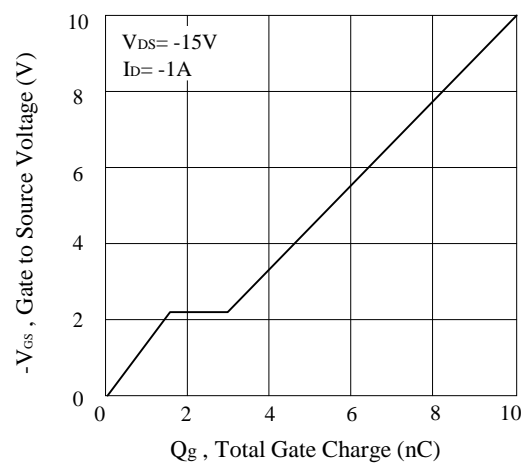
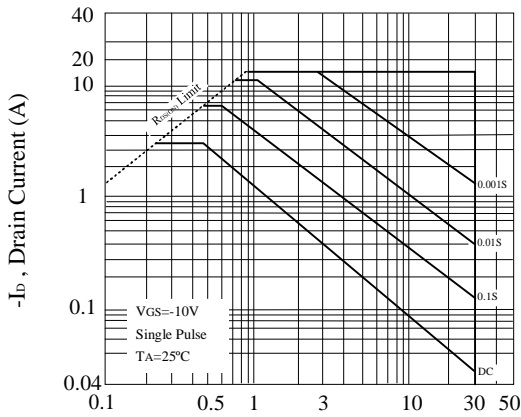
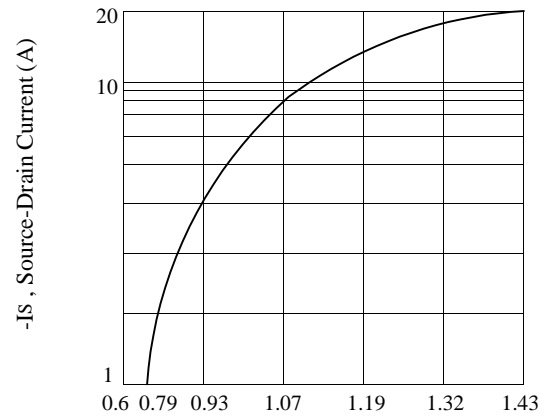


Figure 6. Gate Charge

**TYPICAL CHARACTERISTICS**



-VDS, Drain-Source Voltage (V)  
Figure 7. Maximum Safe Operating Area



-VSD, Body Diode Forward Voltage (V)  
Figure 1. Body Diode Forward Voltage Variation with Source Current

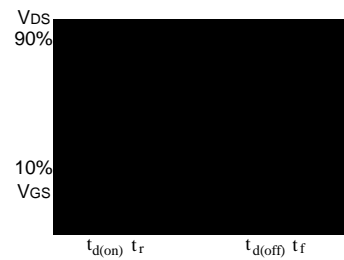
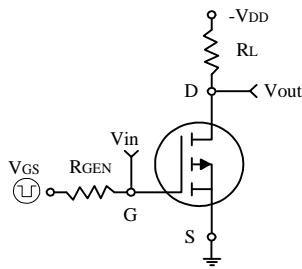


Figure 9. Switching Test Circuit and Switching Waveforms

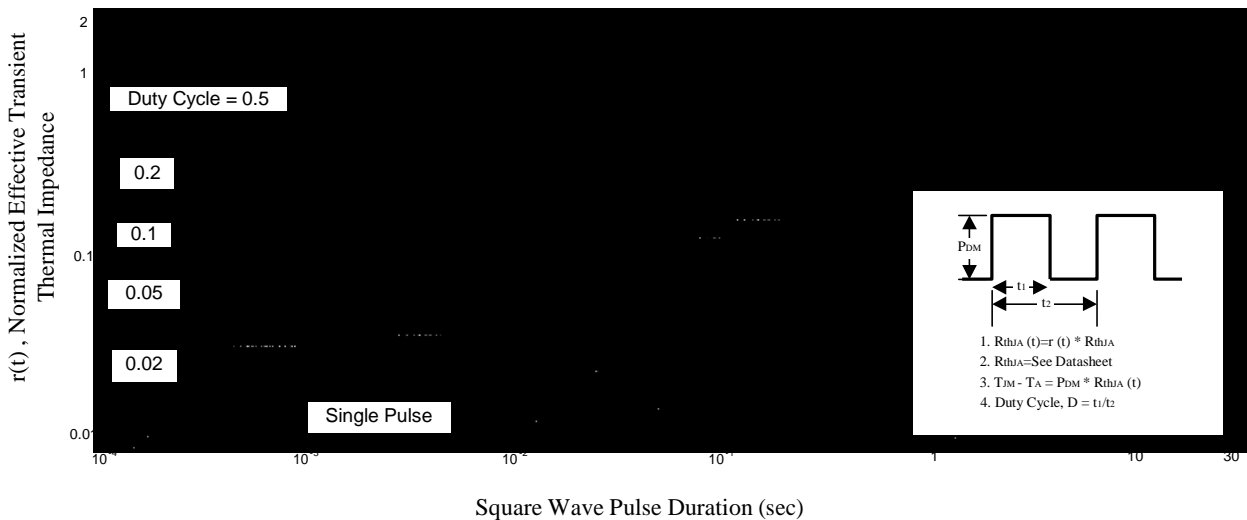


Figure 10. Normalized Thermal Transient Impedance Curve